MB24S THRU MB220S

Voltage Range - 40 to 200 V olts Current - 2.0 Ampere

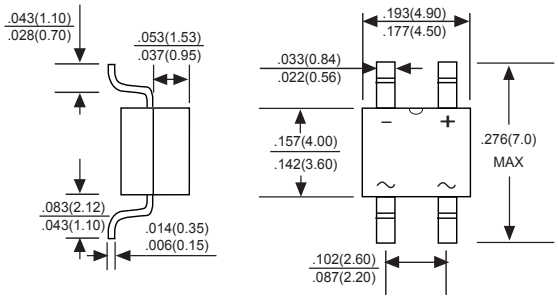
Schottky Surface Mount Flat Bridge Rectifier

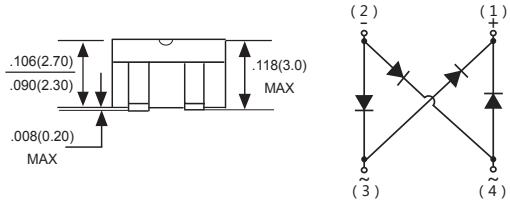
Features

- Ideal for printed circuit board
- Reliable low cost construction utilizing molded plastic technique
- High temperature soldering guaranteed: 260°/10 seconds at 5 lbs., (2.3kg) tension
- Small size, simple installation
- High surge current capability

MBS

RoHS COMPLIANT





Dimensions in inches and (millimeters)

Mechanical Data

Case : JEDEC MBS Molded plastic body
Terminals : Solder plated, solderable per MIL-STD-750,Method 2026
Polarity : Polarity symbol marking on body
Mounting Position : Any
Weight : 0.008 ounce, 0.22 grams

Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unlss otherwise specified.

Single phase half-wave 60Hz,resistive or inductive load,for capacitive load current derate by 20%.

Parameter / Marking Code	SYMBOLS	MDD MB24S	MDD MB26S	MDD MB28S	MDD MB210S	MDD MB220S	UNITS
Maximum repetitive peak reverse voltage	V_{RRM}	40	60	80	100	200	V
Maximum RMS voltage	V_{RMS}	28	42	56	70	140	V
Maximum DC blocking voltage	V_{DC}	40	60	80	100	200	V
Maximum average forward rectified current	$I_{F(AV)}$	2.0					A
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	50		40			A
Maximum instantaneous forward voltage at 2A	V_F	0.55	0.70	0.85			V
Maximum DC reverse current T_A=25°C at rated DC blocking voltage T_A=100°C	I_R	0.5 10		0.3 5			mA
Typical junction capacitance at 4.0V,1.0MHz	C_j	220	80				pF
Typical thermal resistance（Note1）	$R\theta_{JA}$	75					°C/W
Operating temperature range	T_J	-55 to +150					°C
storage temperature range	T_{STG}	-55 to +150					°C

Note：1.Mounted on glass epoxy PC board with 4×1.5"×1.5"（3.81×3.81 cm）copper pad.

Ratings And Characteristic Curves

Fig.1 Forward Current Derating Curve

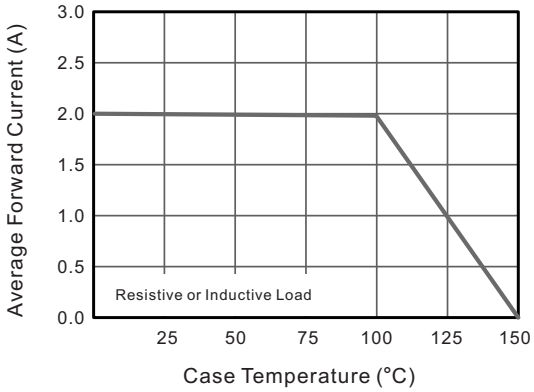


Fig.2 Typical Reverse Characteristics

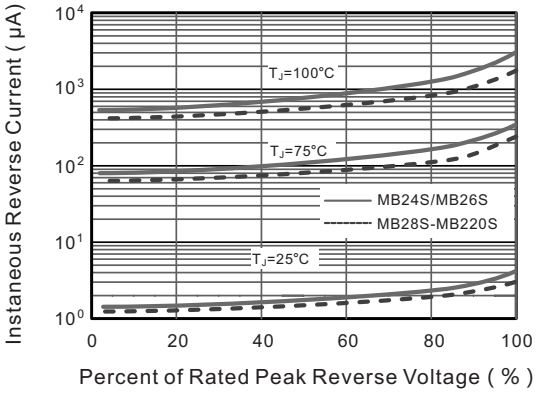


Fig.3 Typical Forward Characteristic

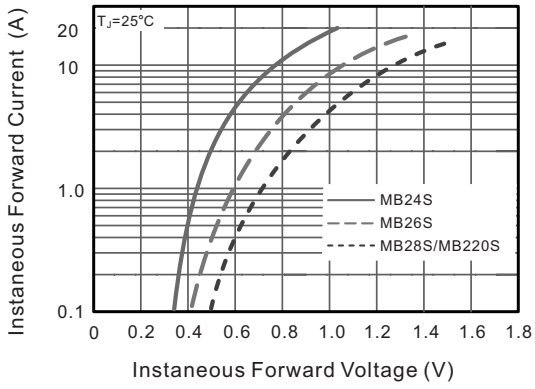


Fig.4 Typical Junction Capacitance

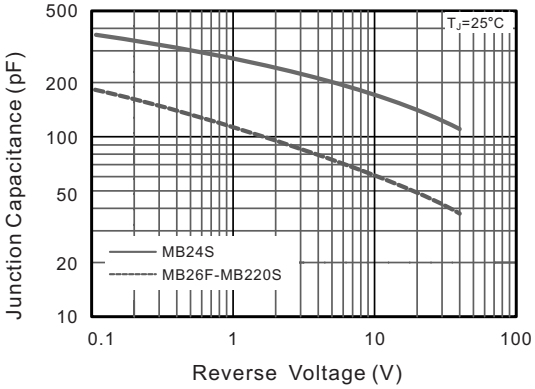


Fig.5 Maximum Non-Repetitive Peak Forward Surage Current

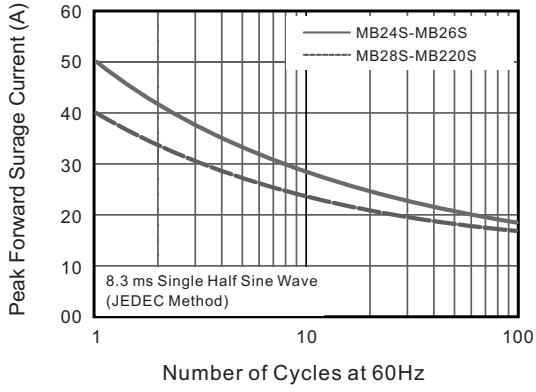
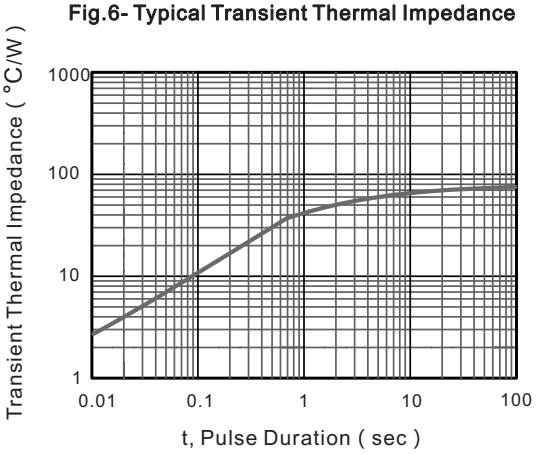
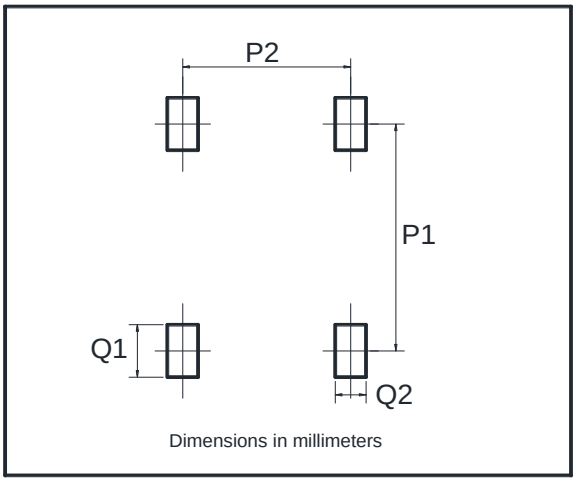


Fig.6- Typical Transient Thermal Impedance



The curve above is for reference only.

Suggested Pad Layout



Dim	Min
P1	6.00
P2	2.40
Q1	1.84
Q2	1.20